

# SED1522

## ■ DESCRIPTION

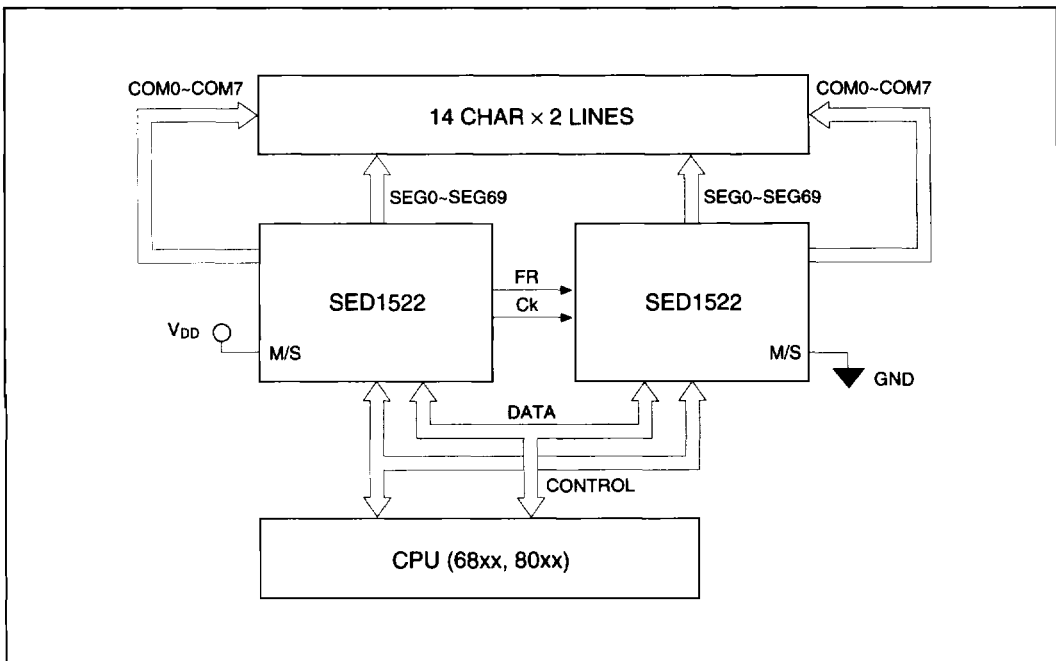
The SED1522 is a graphic LCD controller driver designed for use in a dot matrix LCD (Liquid Crystal Display) system capable of displaying characters and graphics. The bit-addressable display data which is sent from an 8-bit microcomputer is stored in a built-in display RAM which generates the signals required for driving the LCD. The circuitry has been designed to ensure low power consumption and a wide range of operating voltages, for use in high-performance handheld systems that run on batteries.

The SED1522 can use a single chip to drive an LCD of 13 characters by one line each plus an indicator. The SED1522 can be used in master-slave combination. Moreover, the SED1521 segment driver is available for expanding a system to enable 80-port output in order to construct mid-capacity displays using a minimal number of drivers.

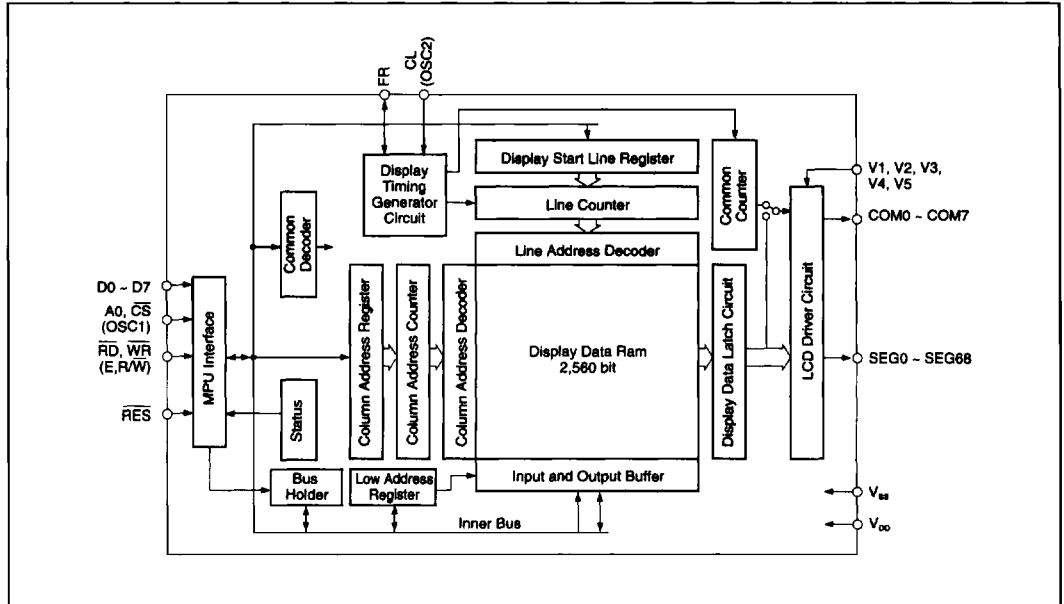
## ■ FEATURES

- Low-power CMOS technology ..... 30 $\mu$ W
- Fast CPU 8-bit data interface (80xx, 68xx)
- 1/8 to 1/16 duty cycle
- Built-in LCD driver circuit ..... 69 segments  
8 commons
- Built-in display data RAM ..... 2560 bits
- Rich display command setting
- On-chip CR oscillation circuit
- Master/slave operation is supported
- LCD voltage ..... -3.5 to -13V
- Single power supply ..... 2.4 to 7.0V
- Package ..... QFP5-100 pin (FOA, FAA)  
QFP15-100 pin (FOC, FAC)  
Al pad (DOA, DAA)  
Au bump (DOB, DAB)

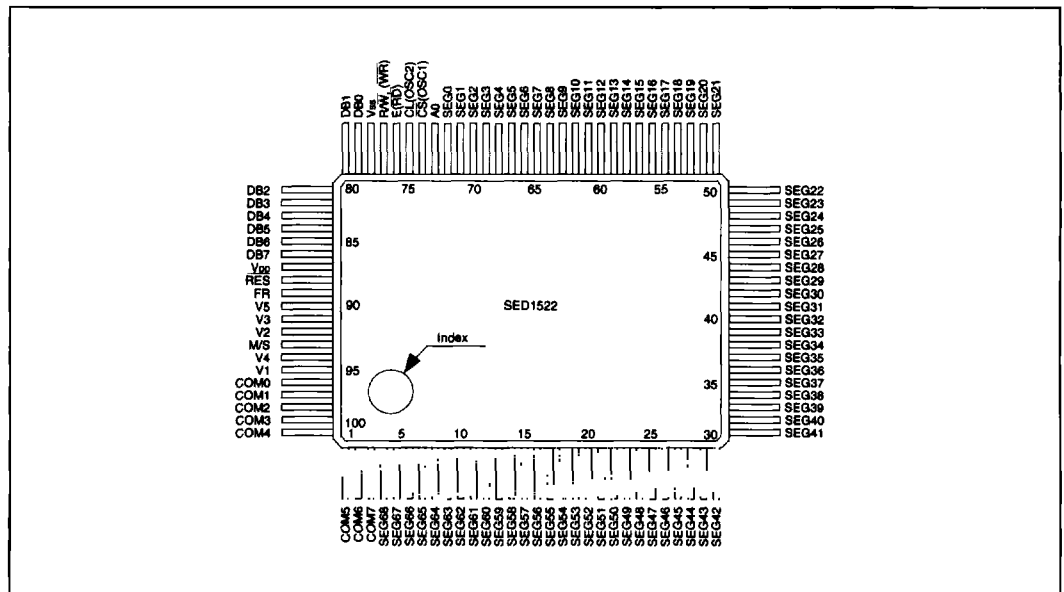
## ■ SYSTEM BLOCK DIAGRAM



■ BLOCK DIAGRAM



■ PINOUT



Model Name	Terminal No.	
	74	75
SED1522FOA	OSC1	OSC2
SED1522FAA	CS	CL

\* The Common output COM0 to COM7 of the Master LSI corresponds COM15 to COM8 on the Slave LSI.

■ PIN DESCRIPTION

Terminal Name	Function
DB0~DB7	Data input
A0	Selects display data or instructions. HIGH: Display data. LOW: Instructions.
RES	Resets the system and selects the interface type for a 68-port/80-port MPU. HIGH: 68-port MPU interface. LOW: 80-port MPU interface.
CS	Chip Select input. LOW: Active level sensing.
E (RD)	Read/Write Enable signal when a 68-port MPU is connected. (Active-LOW Read Enable signal when an 80-port MPU is connected.)
R/W (WR)	Read/Write Select signal when a 68-port MPU is connected. HIGH: Read Select LOW: Write Select (Active-LOW Write Enable input when an 80-port MPU is connected. Rising edge sensing.)
CL	External clock input (only effective with external clock types).
FR	LCD Frame (AC-conversion) signal input/output.
SEG0~SEG68	Segment output for driving the LCD.
COM0~COM7 (COM15~COM8)	Common output for driving the LCD.
M/S	Master/Slave Select signal.
VDD	5V power supply.
VSS	0V power supply (GND level).
V1, V2, V3, V4, V5	Power supplies for driving the LCD. $V_{DD} \geq V1 \geq V2 \geq V3 \geq V4 \geq V5$

■ CLOCK OPTIONS

Model Name	Operating Clock		Connectable Drivers	Package
	Internal oscillator	External clock		
SED1522FOA	18kHz	18kHz	SED1522FOA, SED1521FOA	QFP5-100pin
SED1522DOA			SED1522DOA, SED1521DOA	AL pad chip
SED1522DOB			SED1522DOB, SED1521DOB	Au Bump chip
SED1522FAA	—	2kHz	SED1522FAA, SED1521FAA	QFP5-100pin
SED1522DAA			SED1522DAA, SED1521DAA	AL pad chip
SED1522DAB			SED1522DAB, SED1521DAB	Au Bump chip

■ ELECTRICAL CHARACTERISTICS

● Absolute Maximum Ratings

(V<sub>DD</sub> = 0V, V<sub>DD</sub> ≥ V1 ≥ V2 ≥ V3 ≥ V4 ≥ V5)

Parameter	Symbol	Ratings	Unit
Supply voltage (1)	V <sub>SS</sub>	-8.0 to 0.3	V
Supply voltage (2)	V5	-16.5 to 0.3	V
Supply voltage (3)	V1, V2 V3, V4	V5 to 0.3	V
Input voltage	V <sub>I</sub>	V <sub>SS</sub> -0.3 to 0.3	V
Output voltage	V <sub>O</sub>	V <sub>SS</sub> -0.3 to 0.3	V
Permissible loss	P <sub>D</sub>	250	mW
Operating temperature	T <sub>opr</sub>	-30 to 85	°C
Storage temperature	FP	T <sub>stg</sub>	°C
	Die		
Soldering temperature	T <sub>sol</sub>	260°C for 10s (at the leads)	

● DC Characteristics

(V<sub>DD</sub> = 0V, T<sub>a</sub> = -20 to 75°C)

Parameter		Symbol	Condition	Applicable Terminals	Min	Typ	Max	Unit	
Operating voltage (1)*1	Recommended operation	V <sub>SS</sub>		V <sub>SS</sub>	-5.5	-5.0	-4.5	V	
	Potential operation				-7.0	—	-2.4		
Operating voltage (2)	Recommended operation	V5		V5	-13.0	—	-3.5	V	
	Potential operation				-13.0	—	—		
	Potential operation	V1, V2		V1, V2	0.6×V5	—	V <sub>DD</sub>		
	Potential operation	V3, V4		V3, V4	V5	—	0.4×V5		
HIGH input voltage		V <sub>IHT</sub>		A0, D0-D7, E, R <sub>W</sub> , C <sub>S</sub>	V <sub>SS</sub> +2.0	—	V <sub>DD</sub>	V	
		V <sub>IHC</sub>		CL, FR, M/S, R <sub>ES</sub>	0.2×V <sub>SS</sub>	—	V <sub>DD</sub>		
		V <sub>IHT</sub>	V <sub>SS</sub> = -3V	A0, D0-D7, E, R <sub>W</sub> , C <sub>S</sub>	0.2×V <sub>SS</sub>	—	V <sub>DD</sub>	V	
		V <sub>IHC</sub>	V <sub>SS</sub> = -3V	CL, FR, M/S, R <sub>ES</sub>	0.2×V <sub>SS</sub>	—	V <sub>DD</sub>		
LOW input voltage		V <sub>ILT</sub>		A0, D0-D7, E, R <sub>W</sub> , C <sub>S</sub>	V <sub>SS</sub>	—	V <sub>SS</sub> +0.8	V	
		V <sub>ILC</sub>		CL, FR, M/S, R <sub>ES</sub>	V <sub>SS</sub>	—	0.8×V <sub>SS</sub>		
		V <sub>ILT</sub>	V <sub>SS</sub> = -3V	A0, D0-D7, E, R <sub>W</sub> , C <sub>S</sub>	V <sub>SS</sub>	—	0.85×V <sub>SS</sub>	V	
		V <sub>ILC</sub>	V <sub>SS</sub> = -3V	CL, FR, M/S, R <sub>ES</sub>	V <sub>SS</sub>	—	0.8×V <sub>SS</sub>		
HIGH output voltage		V <sub>OHT</sub>	I <sub>OH</sub> = -3mA	D0-D7	V <sub>SS</sub> +2.4	—	—	V	
		V <sub>OHC1</sub>	I <sub>OH</sub> = -2mA	FR	V <sub>SS</sub> +2.4	—	—		
		V <sub>OHC2</sub>	I <sub>OH</sub> = -120μA	OSC2	0.2×V <sub>SS</sub>	—	—		
		V <sub>OHT</sub>	V <sub>SS</sub> = -3V I <sub>OH</sub> = -2mA	D0-D7	0.2×V <sub>SS</sub>	—	—	V	
		V <sub>OHC1</sub>	V <sub>SS</sub> = -3V I <sub>OH</sub> = -2mA	FR	0.2×V <sub>SS</sub>	—	—		
		V <sub>OHC2</sub>	V <sub>SS</sub> = -3V I <sub>OH</sub> = -50μA	OSC2	0.2×V <sub>SS</sub>	—	—		
LOW output voltage		V <sub>OLT</sub>	I <sub>OL</sub> = 3mA	D0-D7	—	—	V <sub>SS</sub> +0.4	V	
		V <sub>OLC1</sub>	I <sub>OL</sub> = 2mA	FR	—	—	V <sub>SS</sub> +0.4		
		V <sub>OLC2</sub>	I <sub>OL</sub> = 120μA	OSC2	—	—	0.8×V <sub>SS</sub>		
		V <sub>OLT</sub>	V <sub>SS</sub> = -3V I <sub>OL</sub> = 2mA	D0-D7	—	—	0.8×V <sub>SS</sub>	V	
		V <sub>OLC1</sub>	V <sub>SS</sub> = -3V I <sub>OL</sub> = 2mA	FR	—	—	0.8×V <sub>SS</sub>		
		V <sub>OLC2</sub>	V <sub>SS</sub> = -3V I <sub>OL</sub> = 50μA	OSC2	—	—	0.8×V <sub>SS</sub>		
Input leak current		I <sub>LI</sub>		A0, E, R <sub>W</sub> , C <sub>S</sub> , CL, R <sub>ES</sub> , M/S pins	-1.0	—	1.0	μA	
Output leak current		I <sub>LO</sub>	Applicable when FR is in a high-impedance state	D0-D7, FR pins	-3.0	—	3.0		
LCD driver ON resistance		R <sub>ON</sub>	T <sub>a</sub> = 25°C	V5 = -5.0V	SEG0-68	—	5.0	7.5	kΩ
				V5 = -3.5V	COM0-7	—	10.0	50.0	
Static current consumption		I <sub>DDQ</sub>	CS = CL = V <sub>DD</sub>		V <sub>DD</sub>	—	0.05	1.0	
Active current consumption	External CLK	I <sub>DD(1)</sub>	During display	f <sub>CL</sub> = 2kHz	V <sub>DD</sub>	—	2.0	5.0	μA
	Oscillator			R <sub>t</sub> = 1MΩ		—	9.5	15.0	
	External CLK		During display	f <sub>CL</sub> = 2kHz	V <sub>DD</sub>	—	1.5	4.5	μA
	Oscillator			V5 = -5V, V <sub>SS</sub> = -3V		R <sub>t</sub> = 1MΩ	—	6.0	
		I <sub>DD(2)</sub>	During access t <sub>yc</sub> = 200kHz V <sub>SS</sub> = -3V, During access t <sub>yc</sub> = 200kHz			—	300	500	μA
						—	150	300	
Input terminal capacity		C <sub>IN</sub>	T <sub>a</sub> = 25°C, f = 1MHz	All input terminals		—	5.0	8.0	pF
Oscillating frequency		f <sub>OSC</sub>	R <sub>t</sub> = 1.0MΩ ± 2%, V <sub>SS</sub> = -5.0V			15	18	21	kHz
			R <sub>t</sub> = 1.0MΩ ± 2%, V <sub>SS</sub> = -3.0V			11	16	21	
Reset time		t <sub>R</sub>		RES	1.0	—	1000	μs	

\*1. A wide range of operating voltages is guaranteed, except in case of abrupt voltage fluctuations during MPU access.

● AC Characteristics

○ Read/Write timing for the 80-port MPU

(Ta = -20 to 75°C, Vss = -5.0V±10%)

Parameter	Signal	Symbol	Condition	Min	Typ	Max	Unit
Address hold time	A0, $\overline{CS}$	tAH8		10	—	—	ns
Address set-up time		tAW8		20	—	—	ns
System cycle time	$\overline{WR}$ , $\overline{RD}$	tCYC8		1000	—	—	ns
Control pulse width		tCC		200	—	—	ns
Data set-up time	D0~D7	tDS8	CL=100pF	80	—	—	ns
Data hold time		tDH8		10	—	—	ns
$\overline{RD}$ access time		tACC8		—	—	90	ns
Output disable time		tOH8		10	—	60	ns

\*2. The ratings when Vss = -3.0V are approximately 100% higher than when Vss = -5.0V.

\*3. The rise or fall time of input signals should be less than 15ns.

○ Read/Write timing for the 68-port MPU

(Ta = -20 to 75°C, Vss = -5.0V±10%)

Parameter	Signal	Symbol	Condition	Min	Typ	Max	Unit
System cycle time	A0, $\overline{CS}$	tCYC6 *4		1000	—	—	ns
Address set-up time		tAW6		20	—	—	ns
Address hold time	R/W	tAH6		10	—	—	ns
Data set-up time	D0~D7	tDS6		80	—	—	ns
Data hold time		tDH6	10	—	—	ns	
Output disable time		tOH6	10	—	60	ns	
Access time		tACC6	—	—	90	ns	
Enable pulse width		READ	E	tEW	100	—	—
	WRITE	80			—	—	ns

\*4 tCYC6 indicates the cycle during which  $\overline{CS}/E$  are HIGH; it does not indicate the cycle of the E signal.

\*5 The ratings when Vss = -3.0V are approximately 100% higher than when Vss = -5.0V.

\*6 The rise or fall time of input signals should be less than 15ns.

○ Control timing for 80-port/68-port display

(Ta = -20 to 75°C, Vss = -5.0V±10%)

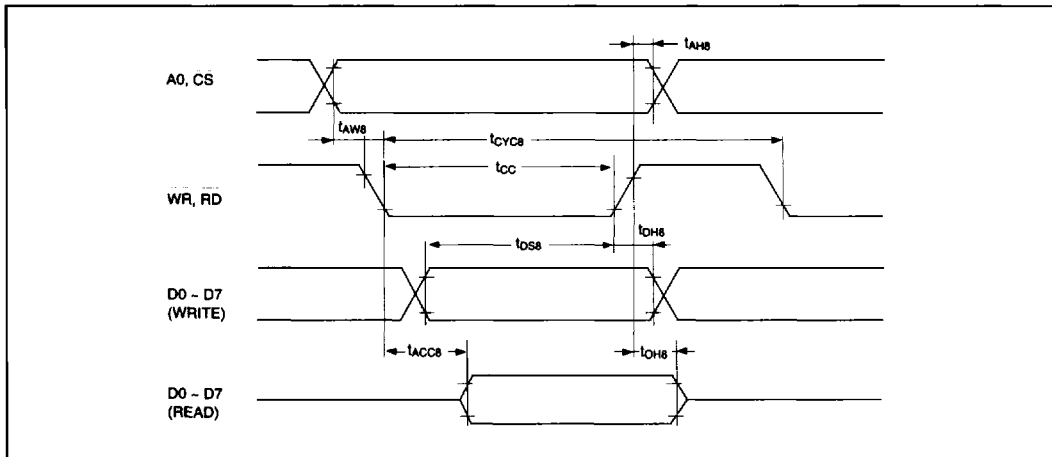
Parameter	Signal	Symbol	Condition	Min	Typ	Max	Unit
LOW pulse width	CL	tWLCL	(Input timing)	35	—	—	μs
HIGH pulse width		tWHCL		35	—	—	μs
Rising time		tr		—	30	150	ns
Falling time		tf		—	30	150	ns
FR delay time	FR	tDFR	(Input timing)	-2.0	0.2	2.0	μs
			(Output timing), CL=100pF	—	0.2	0.4	μs

\*7. The ratings when Vss = -3.0V are approximately 100% higher than when Vss = -5.0V.

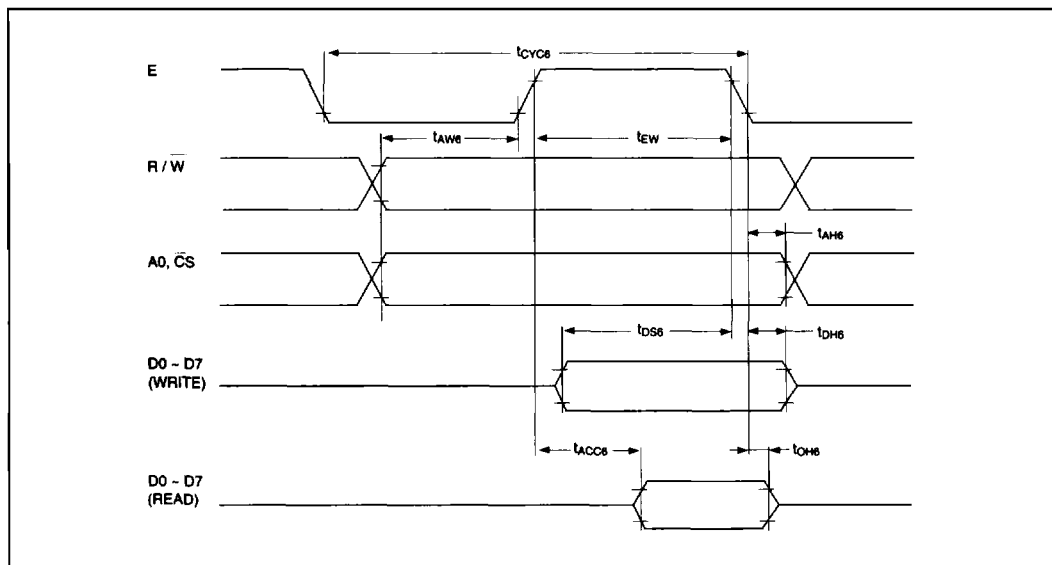
\*8. The input timing of the FR delay time is determined by the SED1522 (Slave).  
The output timing of the FR delay time is determined by the SED1522 (Master).

● Timing Chart

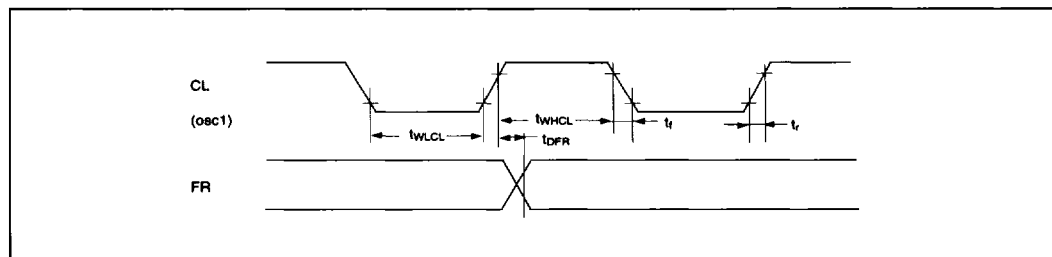
○ Read/Write timing for the 80-port MPU



○ Read/Write timing for the 68-port MPU



○ Control timing for 80-port/68-port display



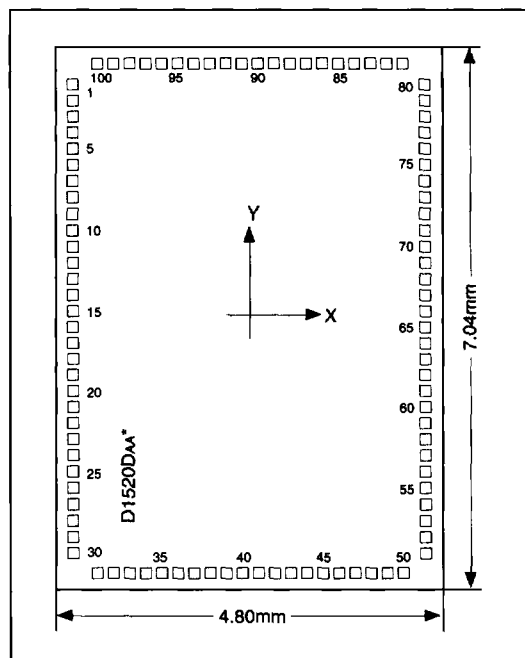
■ DISPLAY COMMANDS

(Based on the 80-port MPU; the RD and WR commands differ for the 68-port MPU)

Command	RDWR A0	D7 D6 D5 D4 D3 D2 D1 D0	Function		
1 Display ON/OFF	1 0 0	1 0 1 0 1 1 1 0/1	Switches the entire display ON or OFF, regardless of the Display RAM's data or the internal status.		
2 Display START Line	1 0 0	1 1 0	Display START address (0-31)	Determines the line of RAM data to be displayed at the display's top line (COM0).	
3 Page Address Set	1 0 0	1 0 1 1 1 0	Page (0-3)	Sets the page of the Display RAM in the page address register.	
4 Column (Segment) Address Set	1 0 0	0	Column address (0-79)	Sets the column address of the Display RAM in the column address register.	
5 Status Read	0 1 0	BUSY ACC ON/OFF RESET	0 0 0 0	Reads the status. BUSY 1: Busy (internal processing) 0: READY status ADC 1: Rightward (forward) output 0: Leftward (reverse) output ON/OFF 1: Display OFF 0: Display ON RESET 1: Resetting 0: Normal	
6 Write Display Data	1 0 1		Write Data	Writes the data on the data bus to RAM	These commands access a previously-specified address of the Display RAM, after which the column address is incremented by one.
7 Read Display Data	0 1 1		Read Data	Reads data from the Display RAM onto the data bus.	
8 ADC Select	1 0 0	1 0 1 0 0 0 0 0/1		Used to reverse the correspondence between the Display RAM's column addresses and segment driver output ports 0: Rightward (forward) output 1: Leftward (reverse) output	
9 Static Drive ON/OFF	1 0 0	1 0 1 0 0 1 0 0/1		Selects normal display operation or static all-lit drive display operation. 1: Static drive (Power Save) *9 0: Normal display operation	
10 Duty Select	1 0 0	1 0 1 0 1 0 0 0/1		Selects the duty factor for driving LCD cells. 1: 1/16 duty 0: 1/8 duty	
11 Read Modify Write	1 0 0	1 1 1 0 0 0 0 0		Increments the column address counter by one only when display data is written but not when it is read.	
12 End	1 0 0	1 1 1 0 1 1 1 0		Cancels the Ready Modify Write mode.	
13 Reset	1 0 0	1 1 1 0 0 0 1 0		Resets the Display START line to the 1st line in the register. Resets the column address counter to 0 and sets page address register to 3.	

\*9. Power Save mode is entered by selecting static drive in Display OFF status.

■ PAD LAYOUT



○ Aluminum pad chip specifications

Chip dimensions: 4.80 × 7.04 × 0.40mm

Pad surface area: 100 × 100μm

○ Gold bump chip specifications (reference only)

Minimum bump pitch: 199μm

Bump height: 20<sup>+10</sup><sub>-5</sub> μm

Bump size: 132 × 111 μm (±20 μm)

Chip dimensions: 4.80 × 7.04 × 0.525mm

\* The die shown is the SED1522DAA. The final A in the suffix indicates that the device is an aluminum pad product. Bump chip products share the same die part number as aluminum products; however, the last letter of the suffix is B.

■ PAD COORDINATES

Pin names are for the SED1522DA/SED1522DB, and those in brackets for the SED1522DOA/SED1522DOB.

Pad No.	Pin Name	X	Y	Pad No.	Pin Name	X	Y
1	COM5	159	6507	51	SEG21	4641	482
2	COM6	159	6308	52	SEG20	4641	681
3	COM7	159	6108	53	SEG19	4641	881
4	SEG68	159	5909	54	SEG18	4641	1080
5	SEG67	159	5709	55	SEG17	4641	1280
6	SEG66	159	5510	56	SEG16	4641	1479
7	SEG65	159	5310	57	SEG15	4641	1679
8	SEG64	159	5111	58	SEG14	4641	1878
9	SEG63	159	4911	59	SEG13	4641	2078
10	SEG62	159	4712	60	SEG12	4641	2277
11	SEG61	159	4512	61	SEG11	4641	2477
12	SEG60	159	4169	62	SEG10	4641	2676
13	SEG59	159	3969	63	SEG9	4641	2876
14	SEG58	159	3770	64	SEG8	4641	3075
15	SEG57	159	3570	65	SEG7	4641	3275
16	SEG56	159	3371	66	SEG6	4641	3474
17	SEG55	159	3075	67	SEG5	4641	3674
18	SEG54	159	2876	68	SEG4	4641	3948
19	SEG53	159	2676	69	SEG3	4641	4148
20	SEG52	159	2477	70	SEG2	4641	4347
21	SEG51	159	2277	71	SEG1	4641	4547
22	SEG50	159	2078	72	SEG0	4641	4789
23	SEG49	159	1878	73	A0	4641	5048
24	SEG48	159	1679	74	CS (OSC1)	4641	5247
25	SEG47	159	1479	75	CL (OSC2)	4641	5447
26	SEG46	159	1280	76	E (RD)	4641	5646
27	SEG45	159	1080	77	R/W (WR)	4641	5846
28	SEG44	159	881	78	Vss	4641	6107
29	SEG43	159	681	79	DB0	4641	6307
30	SEG42	159	482	80	DB1	4641	6506
31	SEG41	504	159	81	DB2	4295	6884
32	SEG40	704	159	82	DB3	4095	6884
33	SEG39	903	159	83	DB4	3896	6884
34	SEG38	1103	159	84	DB5	3696	6884
35	SEG37	1302	159	85	DB6	3497	6884
36	SEG36	1502	159	86	DB7	3297	6884
37	SEG35	1701	159	87	VDD	3098	6884
38	SEG34	1901	159	88	RES	2898	6884
39	SEG33	2100	159	89	FR	2699	6884
40	SEG32	2300	159	90	V5	2499	6884
41	SEG31	2499	159	91	V3	2300	6884
42	SEG30	2699	159	92	V2	2100	6884
43	SEG29	2898	159	93	M/S	1901	6884
44	SEG28	3098	159	94	V4	1701	6884
45	SEG27	3297	159	95	V1	1502	6884
46	SEG26	3497	159	96	COM0	1302	6884
47	SEG25	3696	159	97	COM1	1103	6884
48	SEG24	3896	159	98	COM2	903	6884
49	SEG23	4095	159	99	COM3	704	6884
50	SEG22	4295	159	100	COM4	504	6884

**Note:** Values in the properties table are specified as Max or Min according to the comparison on the numerical coordinates.

All specifications of this device are subject to change without notice.